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 $I_{FAV} = 2x 20 A$ 



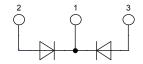
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# **Sonic Fast Recovery Diode**

High Performance Fast Recovery Diode Low Loss and Soft Recovery Common Cathode

Part number

DHG 40 C 1200 HB



# 1 3

1200 V

200 ns

Backside: cathode

#### Features / Advantages:

- Planar passivated chips
- Very low leakage current
- Very short recovery time
- · Improved thermal behaviour
- Very low Irm-values
- Very soft recovery behaviour
- Avalanche voltage rated for reliable operation
- Soft reverse recovery for low EMI/RFI
- Low Irm reduces:
  - Power dissipation within the diode
  - Turn-on loss in the commutating switch

### **Applications:**

- Antiparallel diode for high frequency switching devices
- Antisaturation diode
- Snubber diode
- Free wheeling diode
- Rectifiers in switch mode power supplies (SMPS)
- Uninterruptible power supplies (UPS)

## Package:

 $V_{RRM} =$ 

- Housing: TO-247
- Industry standard outline
- Epoxy meets UL 94V-0
- RoHS compliant

#### Ratings

Symbol	Definition	Conditions		min.	typ.	max.	Unit
$V_{RRM}$	max. repetitive reverse voltage		T <sub>VJ</sub> = 25°C			1200	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 1200 V	$T_{VJ} = 25^{\circ}C$			25	μΑ
		V <sub>R</sub> = 1200 V	$T_{VJ} = 125$ °C			0.4	mA
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 20 A	$T_{VJ} = 25^{\circ}C$			2.24	V
		$I_F = 40 A$				2.89	V
		I <sub>F</sub> = 20 A	T <sub>VJ</sub> = 125°C			2.24	V
		$I_F = 40 A$				3.15	V
I <sub>FAV</sub>	average forward current	rectangular d = 0.5	$T_{\rm C} = 95^{\circ}C$			20	Α
V <sub>F0</sub>	threshold voltage $T_{VJ} = 150 ^{\circ}\text{C}$					1.29	V
r <sub>F</sub>	slope resistance	calculation only				43	mΩ
R <sub>thJC</sub>	thermal resistance junction to case					0.90	K/W
T <sub>VJ</sub>	virtual junction temperature			-55		150	°C
P <sub>tot</sub>	total power dissipation		$T_{\rm C}$ = 25°C			140	W
I <sub>FSM</sub>	max. forward surge current	t = 10 ms (50 Hz), sine	T <sub>VJ</sub> = 45°C			150	Α
I <sub>RM</sub>	max. reverse recovery current		$T_{VJ} = 25^{\circ}C$		15		Α
		$I_F = 20 \text{ A}; V_R = 600 \text{ V}$	$T_{VJ} = 125$ °C		20		Α
t <sub>rr</sub>	reverse recovery time	$-di_F/dt = 400 A/\mu s$	$T_{VJ} = 25^{\circ}C$		200		ns
			$T_{VJ} = 125$ °C		350		ns
C¹	junction capacitance	V <sub>R</sub> = 600 V; f = 1 MHz	T <sub>VJ</sub> = 25°C		8		pF

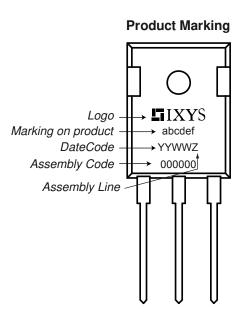


# DHG 40 C 1200 HB

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				Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit	
I <sub>RMS</sub>	RMS current	per terminal 1)			70	Α	
R thCH	thermal resistance case to heatsin	k		0.25		K/W	
T <sub>stg</sub>	storage temperature		-55		150	°C	
Weight				6		g	
M <sub>D</sub>	mounting torque		0.8		1.2	Nm	
F <sub>c</sub>	mounting force with clip		20		120	N	

 $<sup>^{1)}</sup>$   $I_{\text{RMS}}$  is typically limited by the pin-to-chip resistance (1); or by the current capability of the chip (2). In case of (1) and a common cathode/anode configuration with a non-isolated backside, the current capability can be increased by connecting the backside.



#### Part number

D = Diode

H = Sonic Fast Recovery Diode

G = extreme fast

40 = Current Rating [A]

C = Common Cathode

1200 = Reverse Voltage [V] HB = TO-247AD (3)

Standard DHG 40 C 1200 HB DHG40C1200HB Tube 30		Quantity	Delivery Mode	Marking on Product	Ordering Number	Ordering
Standard Brid 40 0 1200 Fib Brid 400 1200 Fib	505138	30	Tube	DHG40C1200HB	DHG 40 C 1200 HB	Standard

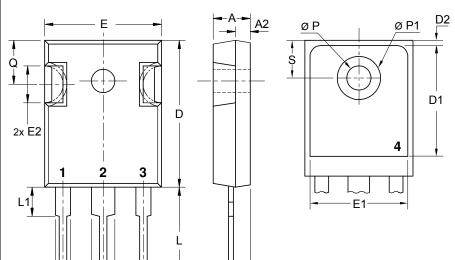




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## **Outlines TO-247**

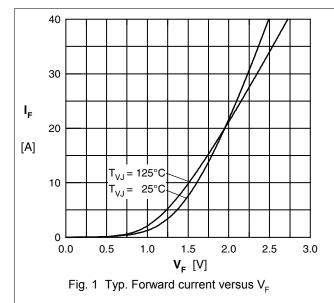
2x b2



−3x b

Sym.	Inches		Millimeter		
	min.	max.	min.	max.	
Α	0.185	0.209	4.70	5.30	
A1	0.087	0.102	2.21	2.59	
A2	0.059	0.098	1.50	2.49	
D	0.819	0.845	20.79	21.45	
E	0.610	0.640	15.48	16.24	
E2	0.170	0.216	4.31	5.48	
е	0.215	BSC	5.46 BSC		
L	0.780	0.800	19.80	20.30	
L1	-	0.177	-	4.49	
ØР	0.140	0.144	3.55	3.65	
Q	0.212	0.244	5.38	6.19	
S	0.242 BSC		6.14 BSC		
b	0.039	0.055	0.99	1.40	
b2	0.065	0.094	1.65	2.39	
b4	0.102	0.135	2.59	3.43	
С	0.015	0.035	0.38	0.89	
D1	0.515	-	13.07	-	
D2	0.020	0.053	0.51	1.35	
E1	0.530	-	13.45	-	
Ø P1	-	0.29	-	7.39	

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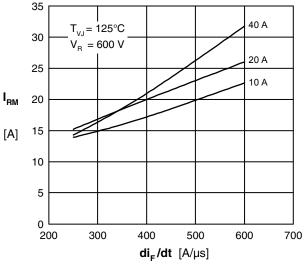


Fig. 3 Typ. peak reverse current I<sub>RM</sub> vs. di/dt

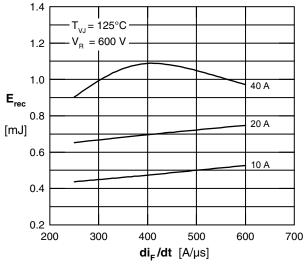


Fig. 5 Typ. recovery energy  $E_{\rm rec}$  versus di/dt

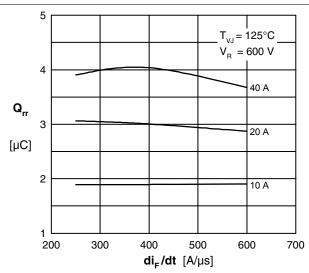


Fig. 2 Typ. reverse recov.charge Q<sub>rr</sub>vs. di/dt

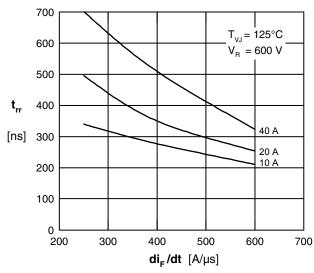


Fig. 4 Typ. recovery time t<sub>rr</sub> versus di/dt

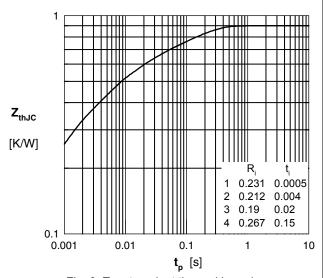


Fig. 6 Typ. transient thermal impedance